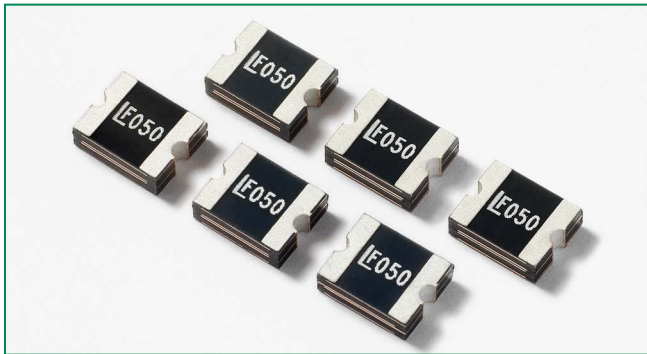


2016L Series



Description

The 2016L Series PTC provides surface mount overcurrent protection for low voltage ($\leq 60V$) applications where resettable protection is desired.



Features

- RoHS compliant, lead-free and halogen-free
- High voltage
- Fast response to fault currents
- Low-profile



Applications

- IEEE 1394 port protection
- Powered ethernet port protection (IEEE 802.3 af)
- Automotive electronic control module protection
- Low voltage telecom equipment protection

Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E183209
	R50119118

Electrical Characteristics

Part Number	Marking	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	P_d typ. (W)	Maximum Time To Trip		Resistance		Agency Approvals	
							Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)		
2016L030	LF030	0.30	0.60	60	20	1.40	1.5	3.0	0.500	2.300	X	X
2016L050	LF050	0.55	1.10	60	20	1.40	2.5	5.0	0.200	1.000	X	X
2016L075/60	LF075-60	0.75	1.50	60	20	1.40	8.0	0.5	0.130	0.900	X	X
2016L100	LF100	1.10	2.20	15	40	1.40	8.0	0.5	0.100	0.400	X	X
2016L100/33	LF100-33	1.10	2.20	33	40	1.40	8.0	0.5	0.100	0.400	X	X
2016L150	LF150	1.50	3.00	15	40	1.40	8.0	1.0	0.070	0.180	X	X
2016L200	LF200	2.00	4.20	6	40	1.40	8.0	3.0	0.048	0.100	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{typ} = Typical resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

* Agency Approval is Pending

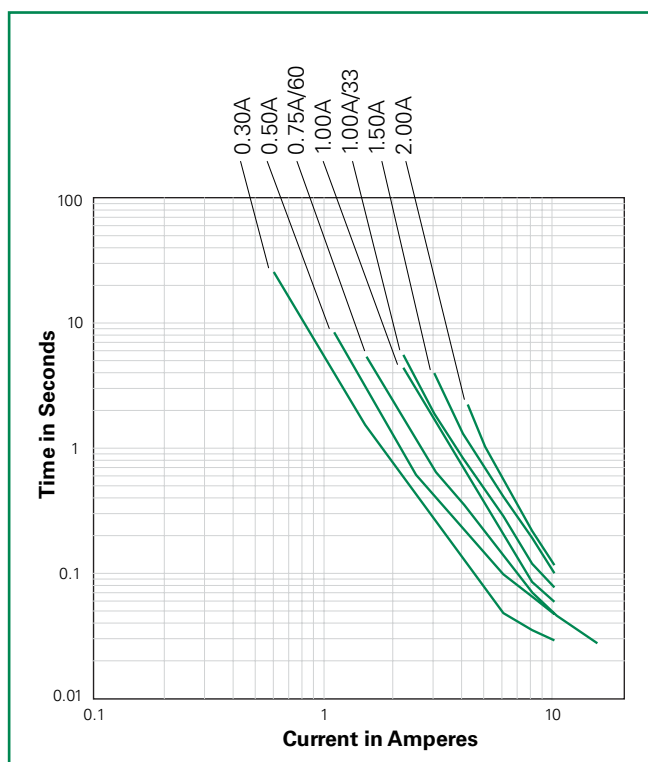
WARNING

- Users shall independently assess the suitability of these devices for each of their applications
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses
- Circuits with inductance may generate a voltage ($L di/dt$) above the rated voltage of the PPTC device.

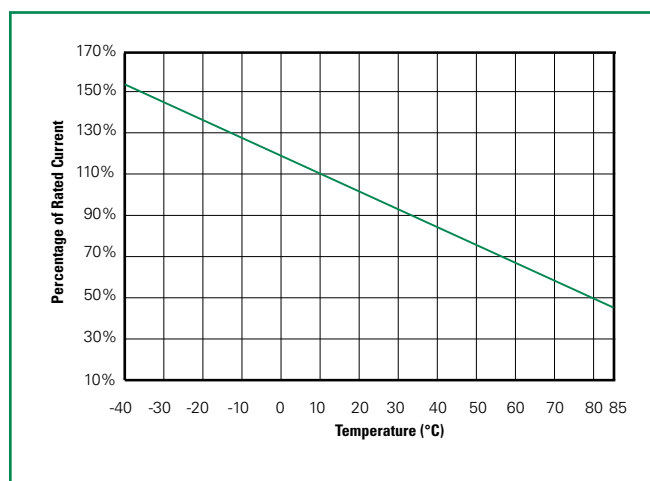
Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
	Hold Current (A)								
2016L030	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.18	0.14
2016L050	0.93	0.80	0.65	0.50	0.42	0.38	0.33	0.30	0.23
2016L075/60	1.21	1.06	0.91	0.75	0.61	0.54	0.45	0.38	0.26
2016L100	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
2016L100/33	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
2016L150	2.26	2.00	1.76	1.50	1.24	1.13	1.00	0.87	0.68
2016L200	2.80	2.50	2.19	2.00	1.84	1.74	1.50	1.34	1.14

Average Time Current Curves



Temperature Derating Curve

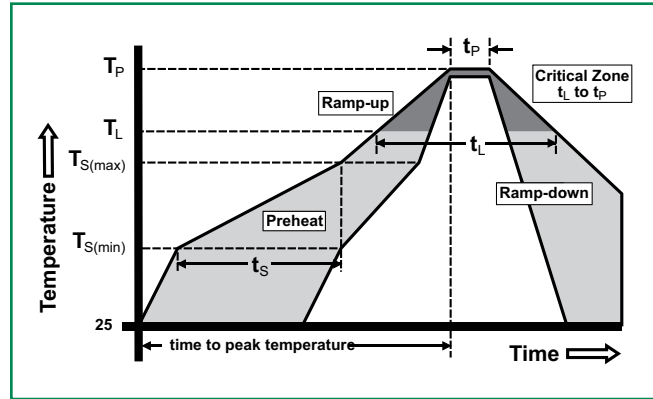


Note:
Typical Temperature derating curve, refer to table for derating data

The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Soldering Parameters

Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{S(max)}$ to T_P)		3°C/second max
Pre Heat:	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (Min to Max) (t_s)	60 – 180 secs
Time Maintained Above:	Temperature (T_L)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak / Classification Temperature (T_P)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.



- All temperature refer to topside of the package, measured on the package body surface
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead
- Recommended maximum paste thickness is 0.25mm (0.010inch)
- Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

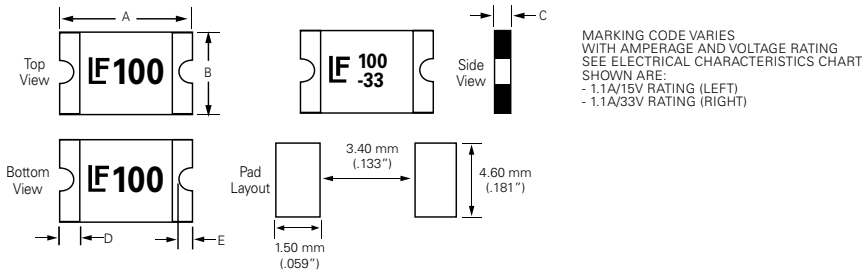
Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin(Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

Environmental Specifications

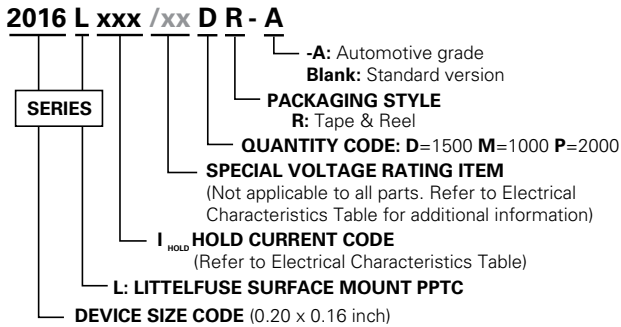
Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+5% typical resistance change
Humidity Aging	+85°C, 85%, R.H., 1000 hours -/+5% typical resistance change
Thermal Shock	MIL-STD-202, Method 107 +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883, Method 2007, Condition A No change
Moisture Sensitivity Level	Level 1, J-STD-020

Dimensions (mm)



Part Number	A		B		C		D		E											
	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm										
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max										
2016L030																				
2016L050																				
2016L075/60																				
2016L100	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.02	0.03	0.50	0.75	0.01	0.06	0.3	1.5	0.01	0.03	0.25	0.65
2016L100/33									0.03	0.05	0.75	1.25								
2016L150									0.03	0.06	0.75	1.55								
2016L200									0.02	0.03	0.50	0.75								

Part Ordering Number System



Packaging

Part Number	Ordering Number	Halogen Free	I _{hold} (A)	I _{hold} Code	Voltage Option	Packaging Option	Quantity	Quantity & Packaging Codes
2016L030	2016L030DR	Yes	0.30	030		Tape and Reel	1500	DR
2016L050	2016L050MR	Yes	0.55	050		Tape and Reel	1000	MR
2016L075/060	2016L075/60MR	Yes	0.75	075	/60	Tape and Reel	1000	MR
2016L100	2016L100PR	Yes	1.10	110		Tape and Reel	2000	PR
2016L100/33	2016L100/33DR	Yes	1.10	110	/33	Tape and Reel	1500	DR
2016L150	2016L150DR	Yes	1.50	150		Tape and Reel	1500	DR
2016L200	2016L200PR	Yes	2.00	200		Tape and Reel	2000	PR

Tape and Reel Specifications

TAPE SPECIFICATIONS: EIA-481-1 (mm)			
	2016L100 2016L200	2016L030 2016L100/33 2016L150	2016L050 2016L075/60
W	12.0+/-0.30	12.0+/-0.30	12.0+/-0.30
F	5.50+/-0.05	5.50+/-0.05	5.50+/-0.05
E₁	1.75+/-0.10	1.75+/-0.10	1.75+/-0.10
D₀	1.55+/-0.05	1.55+/-0.05	1.55+/-0.05
D₁	1.50 (MIN)	1.50 (MIN)	1.50 (MIN)
P₀	4.0+/-0.10	4.0+/-0.10	4.0+/-0.10
P₁	8.0+/-0.10	8.0+/-0.10	8.0+/-0.10
P₂	2.0+/-0.05	2.0+/-0.05	2.0+/-0.05
A₀	4.40+/-0.10	4.48+/-0.10	4.45+/-0.10
B₀	5.50+/-0.10	5.40+/-0.10	5.48+/-0.10
T	0.25+/-0.10	0.25+/-0.10	0.25+/-0.10
K₀	0.80+/-0.10	1.36+/-0.10	1.86+/-0.10
<i>Leader Min.</i>	390	390	390
<i>Trailer Min.</i>	160	160	160

REEL DIMENSIONS: EIA-481-1 (mm)	
C	Ø178.0+/-1.0
D	Ø60.2+/-0.5
H	16.0+/-0.5
W	13.2+/-1.5

Tape and Reel Diagram

